/ Revised record

A	2019.12.24				
A	2021-12-24	6-7	TO-252#		
A	2022-6-17		BRCS50N06DP 251		

BRCS50N06IP

Rev.A Jun.-2022

DATA SHEET

/ Descriptions

TO-251 N ! " # $ % & '

N-CHANNE? @OSFET in a TO-251 Plastic Package.

/ Features

$_{\mathrm{DS(on)}}$ ( ) * + , -) $_{\mathrm{rss}}$ ( ) . / 0 1 2) ! 3 4 5) 6 7 8 9 '

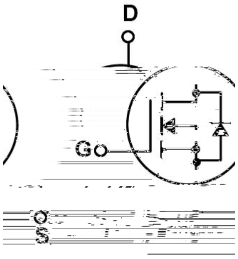
?ow R$_{\mathrm{DSJonK}}$,low gate charge, low C$_{\mathrm{rss}}$, fast switching, Trench Technologies, HF Product.

/ Applications

: ; - < + = > ? @ A + = B C D B E F G 8 9 H + I J $ C D '

Suited for low voltage applications such as automotive, DC/DC Converters, and high efficiency switching for power management in portable and battery operated products.

/ Equivalent Circuit



/ Pinning

PIN1 ? G PIN 2 ? D PIN 3 ? S

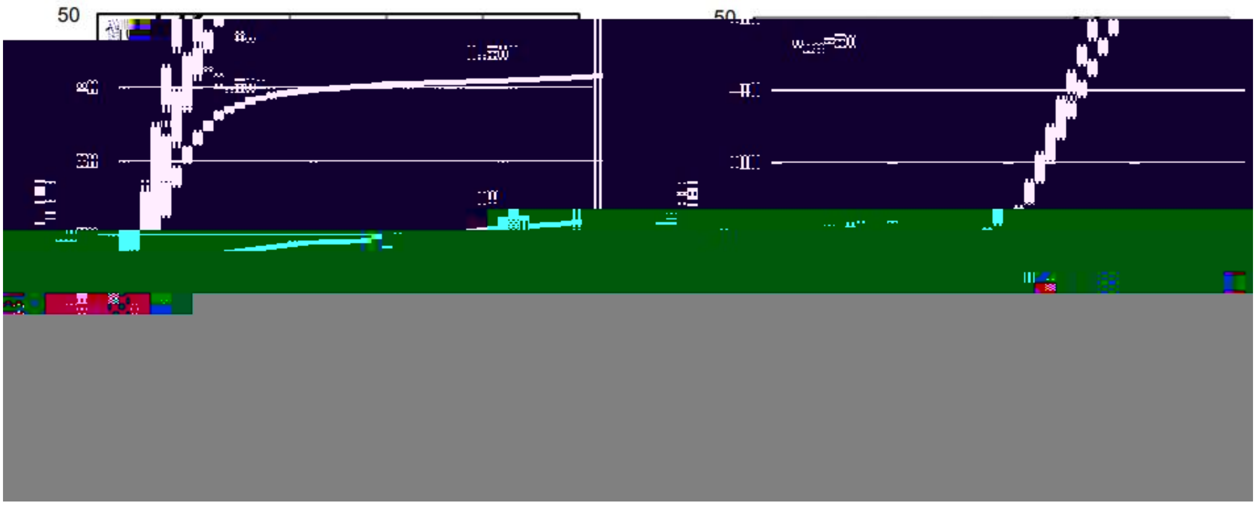
/ Marking

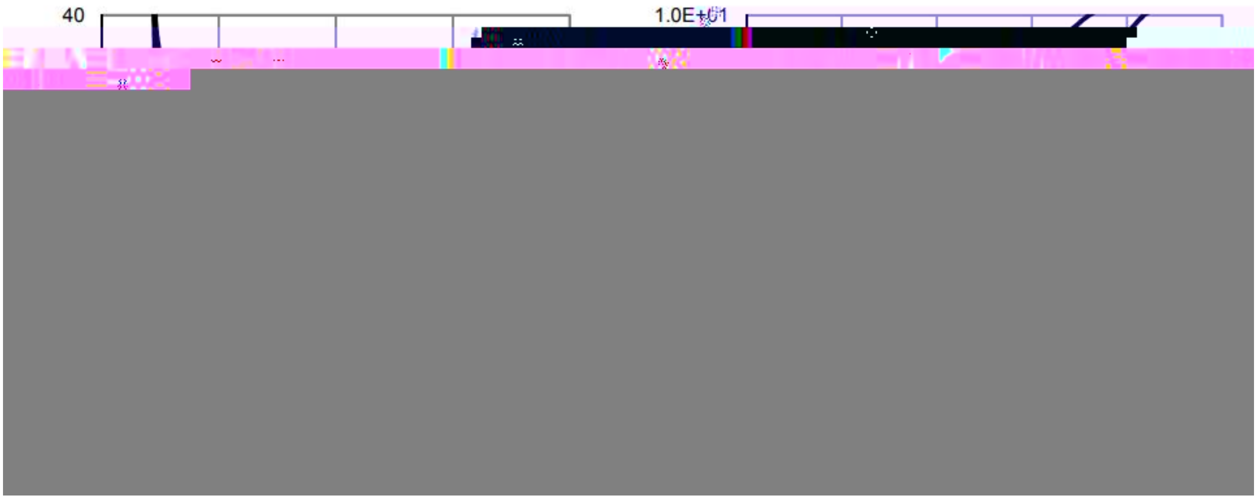
K L M N O ' See @arking Instructions.

Parameter	Symbol	Rating	Rnit
Drain-Source Soltage	S_{DSS}	60	S

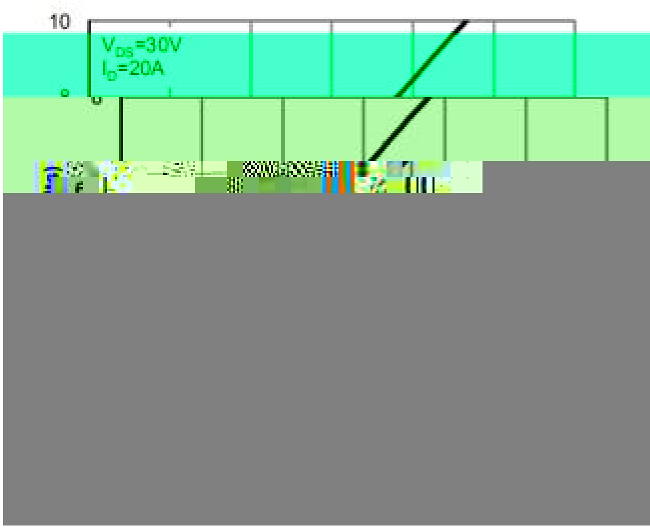
[redacted]

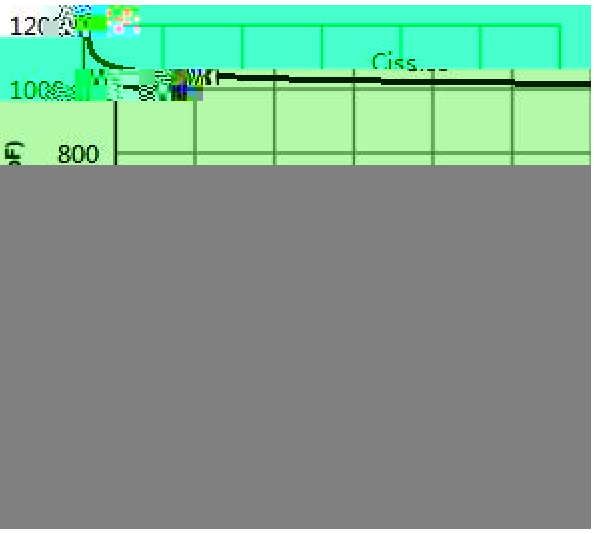
/ Electrical Characteristic Curve

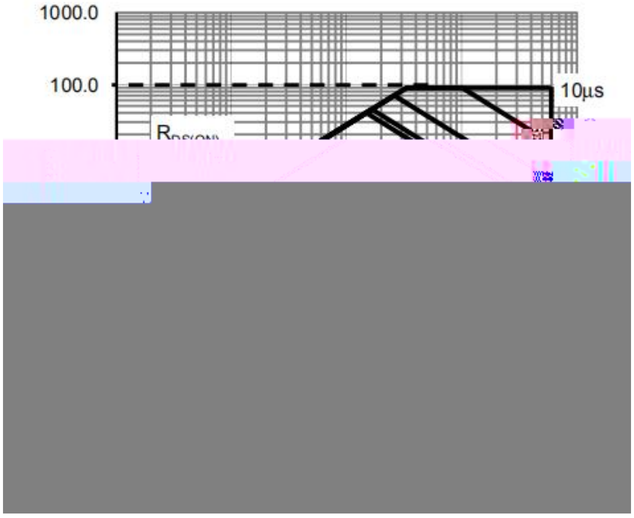




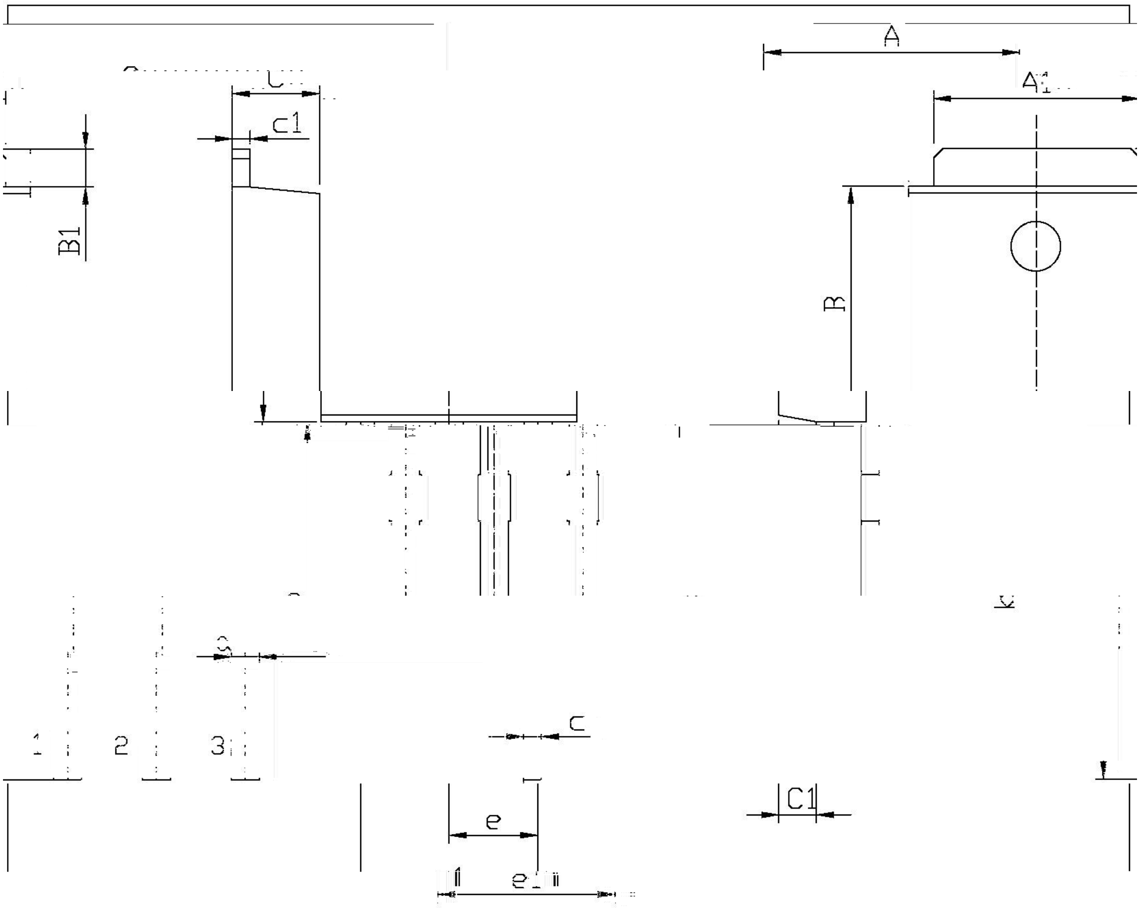
/ Electrical Characteristic Curve







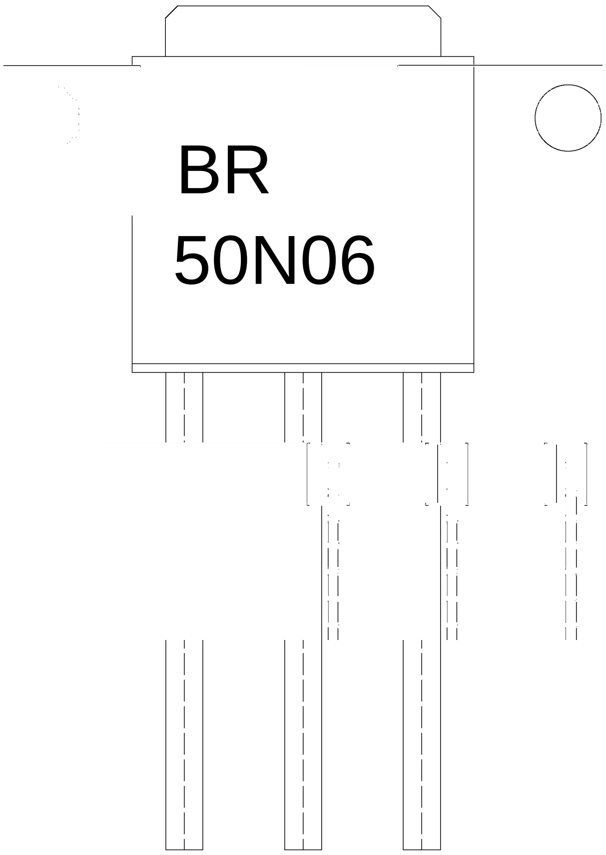
/ Package Dimensions



单位

Dimensions In Millimeters			Dimensions In Millimeters		
	Min	Max		Min	Max
[illegible]	0.45	0.55	B	5.95	6.25

/ Marking Instructions



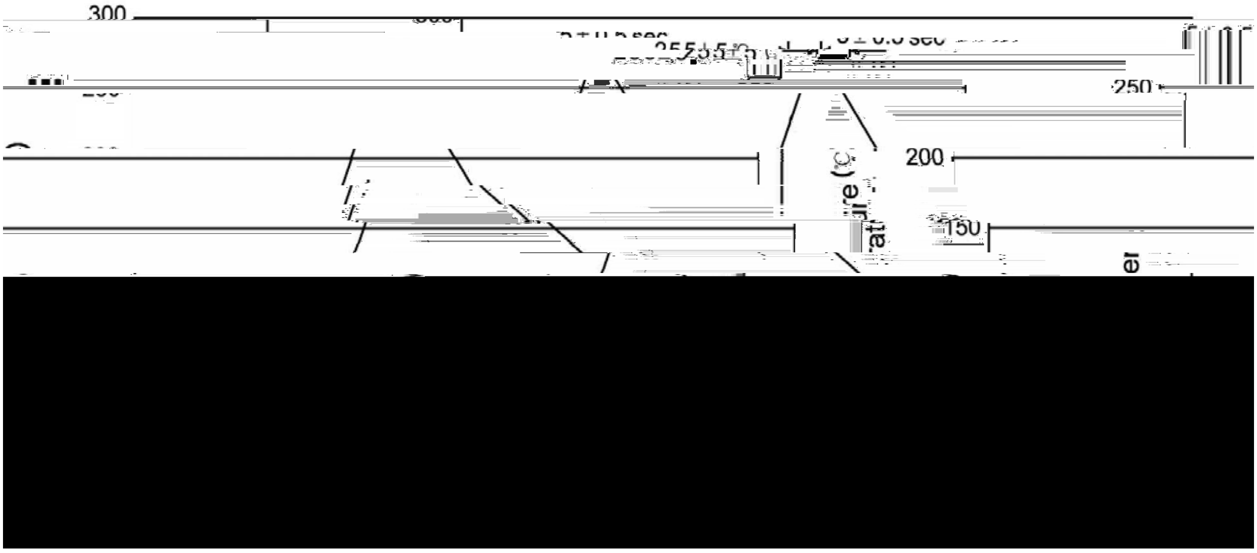
说明：

BR：	为公司代码
50N06：	为型号代码
****：	为生产批号代码，随生产批号变化

Note:

BR:	Company Code
50N06:	Product Type Code
****:	?ot No. Code, code change with ?ot No

( ) / Temperature Profile for Dip Soldering(Pb-Free)



	Note:
1 25 150 60 90sec;	1.Preheating:25~150 , Time:60~90sec.
2 255±5 5±0.5sec;	2.Peak Temp.:255±5 , Duration:5±0.5sec.
3 2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5	10±1 sec.	Temp.:270±5	Time:10±1 sec

/ Packaging SPEC.

/ BR?K

Package Type 封装形式	Rnits 包装数量		Dimension 包装尺寸 Junit: mm^{3}K
	只袋	袋盒	